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,		V 0 8 2000		U.S. PAT	ENT DOCUMENTS				
EXAMINER INITIAL	New York	DESCRIPTION NUMBER	DATE		NAME	CLASS	SUBCLASS	ł	G DATE OPRIATE
Th	A	5,445,996	8/95	Kodera	Kodera et al.		633		
- 111	В	5,486,493	1/96	Jeng	Jeng		623		
TU	C	5,399,235	3/95	Mutsae	Mutsaers et al.		633		
711	D	5,420,075	5/95	Homma	Homma et al.		624		
Tli	D	5,599,740	2/97	Jang et	Jang et al.		626		
TU	F	5,677,239	10/97	Isobe	Isobe		633		
TUI	G	5,795,829	8/98	Shen	Shen		694		
711	Н	5,708,303	1/98	Jeng	Jeng		758		
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	•			OTHER I	DOCUMENTS (Incl.	iding Author, Title,	Date, Pertinent Pa	ges, Etc.)	-
74		M.K. Jain et al., "Adv Low-K Interlevel Diel California, October 19	anced Metalizati ectric Architectu 96.	ion and Inter res for Capa	connect Systems for acitance Reduction,"	ULSI Application Conference at Un	is: Homogenous iversity of Califo	and Mult ornia, Berl	ilayer keley,

Tetsuva Homma, "Fluorinated SiO2 Films for Interlayer Dielectrics in Quarter-Micron ULSI Multilevel Interconnections," Mat. Res. Soc. Symp. Proc. Vol. 381, pp. 239-248, 1995.

EXAMINER OTHER CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

INFORMATION DISCLOSURE CITATION

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Application Number

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Applicant(s)

Sandhu, et al.

Filing Date

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Applicant(s)

Group Art Unit

		Filing Date July 28, 2000	Group Art Unit
*EXAMINER INITIAL	OTHER DOCUMENTS (Including Author, T.	itle, Date, Pertinent Pages, Etc.)	
71/j 3	J. Wary et al., "Vacuum-Deposited Parylene AF-4 Interlayer Dielectric Use," DUMIC Conference, p	l: A Thermally Stable, Low Dielectric p. 207-213, February, 1996.	Constant Polymer For
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